

MMBT4401

NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

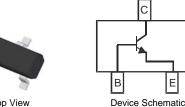
- **Epitaxial Planar Die Construction**
- Complementary PNP Type Available (MMBT4403)
- Ideal for Medium Power Amplification and Switching
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound, • Note 3. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D •
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe • (Lead Free Plating) Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4

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Weight: 0.0082 grams (approximate)



Top View

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6.0	V
Collector Current - Continuous (Note 1)	lc	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	PD	300	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	417	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	°C

1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which Notes: can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

No purposefully added lead. Halogen and Antimony Free. 2.

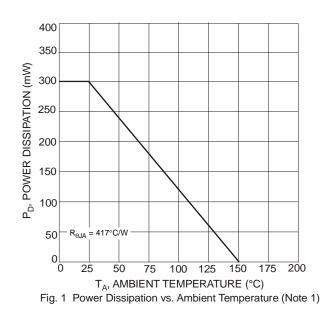
Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date 3 Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

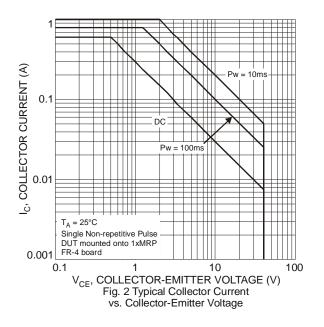


Electrical Characteristics $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 4)					÷		
Collector-Base Breakdown Voltage	V _{(BR)CBO}	60	_	V	$I_{\rm C} = 100 \mu A, I_{\rm E} = 0$		
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	40	—	V	$I_{\rm C} = 1.0 {\rm mA}, I_{\rm B} = 0$		
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	6.0	—	V	$I_{E} = 100 \mu A, I_{C} = 0$		
Collector Cutoff Current	ICEX	_	100	nA	$V_{CE} = 35V, V_{EB(OFF)} = 0.4V$		
Base Cutoff Current	I _{BL}	_	100	nA	$V_{CE} = 35V, V_{EB(OFF)} = 0.4V$		
ON CHARACTERISTICS (Note 4)					· · ·		
DC Current Gain	hre	20 40 80 100 40	 300 	_	$\begin{split} & I_{C} = 100 \mu A, V_{CE} = 1.0 V \\ & I_{C} = 1.0 m A, V_{CE} = 1.0 V \\ & I_{C} = 10 m A, V_{CE} = 1.0 V \\ & I_{C} = 150 m A, V_{CE} = 1.0 V \\ & I_{C} = 500 m A, V_{CE} = 2.0 V \end{split}$		
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	0.40 0.75	V	$I_{C} = 150 \text{mA}, I_{B} = 15 \text{mA}$ $I_{C} = 500 \text{mA}, I_{B} = 50 \text{mA}$		
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.75	0.95 1.2	V	$I_{C} = 150$ mA, $I_{B} = 15$ mA $I_{C} = 500$ mA, $I_{B} = 50$ mA		
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	C _{cb}	_	6.5	pF	$V_{CB} = 5.0V, f = 1.0MHz, I_E = 0$		
Input Capacitance	Ceb		30	pF	$V_{EB} = 0.5V, f = 1.0MHz, I_{C} = 0$		
Input Impedance	h _{ie}	1.0	15	kΩ			
Voltage Feedback Ratio	h _{re}	0.1	8.0	x 10⁻⁴	$V_{CE} = 10V, I_C = 1.0mA,$		
Small Signal Current Gain	h _{fe}	40	500	—	f = 1.0 kHz		
Output Admittance	h _{oe}	1.0	30	μS			
Current Gain-Bandwidth Product	fT	250	—	MHz	$V_{CE} = 10V$, $I_C = 20mA$, f = 100MHz		
SWITCHING CHARACTERISTICS							
Delay Time	t _d	_	15	ns	$V_{CC} = 30V, I_C = 150mA,$		
Rise Time	tr	_	20	ns	$V_{BE(off)} = 2.0V, I_{B1} = 15mA$		
Storage Time	ts	_	225	ns	$V_{CC} = 30V, I_C = 150mA,$		
Fall Time	t _f		30	ns	$I_{B1} = I_{B2} = 15 \text{mA}$		

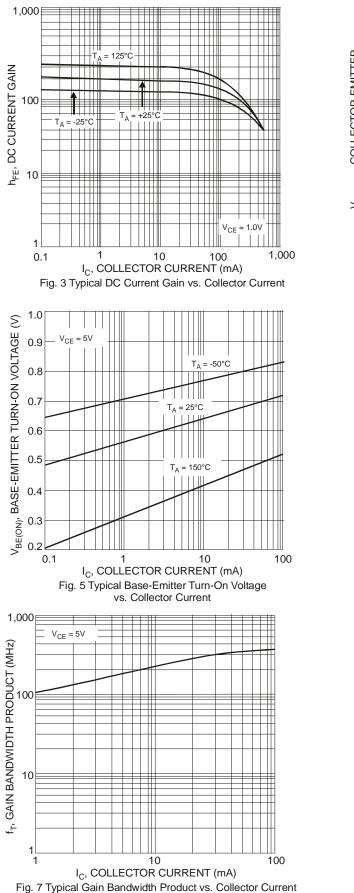
Notes: 4. Short duration pulse test used to minimize self-heating effect.

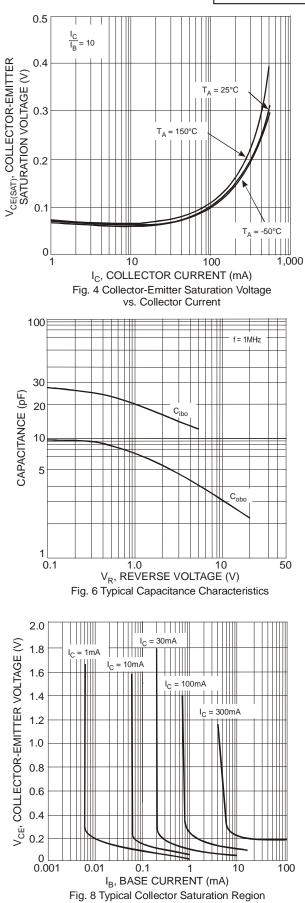














Ordering Information (Note 5)

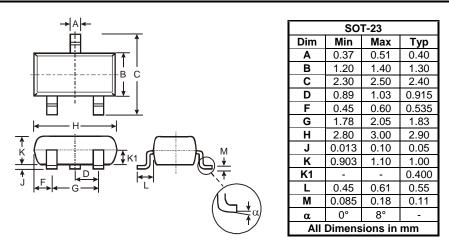
Part Number	Case	Packaging
MMBT4401-7-F	SOT-23	3000/Tape & Reel
MMBT4401-13-F	SOT-23	10,000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

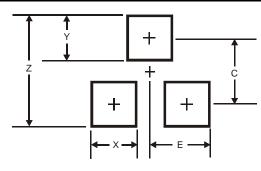
Marking Information

Date Code Ke	٠V					ĸ	2X	¥ ↓	YM = Y = `	= Produ = Date C Year (ex Month (e	Code M :: N = 2	larking 2002)	0	9				
Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	J	K	L	М	Ν	Р	R	S	Т	U	V	W	Х	Y	Z	Α	В	С
Month	Jan	1	Feb	Ma	r	Apr	Ма	y	Jun	Jul		Aug	Sep		Oct	Nov	1	Dec
Code	1		2	3		4	5		6	7		8	9		0	Ν		D

Package Outline Dimensions



Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35

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